| L Number | Hits | Search Text                                | DB                     | Time stamp       |
|----------|------|--|------------------------|------------------|
| 2        | 1350 | (257/777).CCLS.                            | USPAT;                 | 2004/10/27 16:54 |
| '        |      |  | US-PGPUB;              | ,,               |
|          |      |  | EPO; JPO;              |                  |
|          |      |  | DERWENT;               |                  |
|          |      |  | IBM_TDB                |                  |
| 3        | 2613 | 257/777                                    | USPAT;                 | 2004/10/27 16:55 |
|          |      |  | US-PGPUB;              |                  |
|          |      |  | EPO; JPO;              |                  |
|          |      |  | DERWENT;               |                  |
| 4        | 4196 | 257/778                                    | IBM_TDB<br>USPAT;      | 2004/10/27 17:12 |
| 4        | 4190 | 231/116                                    | US-PGPUB;              | 2004/10/2/ 17:12 |
|          |      |  | EPO; JPO;              |                  |
|          |      |  | DERWENT;               |                  |
|          |      | •  | IBM TDB                |                  |
| 5        | 1743 | 257/779                                    | USPAT;                 | 2004/10/27 17:30 |
| -        | _    | · · · · ·                                  | US-PGPUB;              |                  |
|          |      |  | EPO; JPO;              |                  |
|          |      |  | DERWENT;               |                  |
|          |      |  | IBM_TDB                |                  |
| 6        | 2057 | 257/780                                    | USPAT;                 | 2004/10/27 17:45 |
|          |      |  | US-PGPUB;              |                  |
| 1        |      |  | EPO; JPO;              |                  |
|          |      |  | DERWENT;               |                  |
| 7        | 1063 | 257/781                                    | IBM_TDB<br>USPAT;      | 2004/10/27 18:03 |
| '        | 1003 | 231/101                                    | USPAT;<br>US-PGPUB;    | 2004/10/2/ 10:03 |
|          |      |  | EPO; JPO;              | •                |
|          |      |  | DERWENT;               |                  |
|          |      |  | IBM TDB                |                  |
| 8        | 4196 | 257/778                                    | USPAT;                 | 2004/10/27 18:01 |
|          |      |  | US-PGPUB;              |                  |
|          |      |  | EPO; JPO;              |                  |
|          |      |  | DERWENT;               |                  |
|          |      |  | IBM_TDB                |                  |
| 9        | 3831 | 257/723                                    | USPAT;                 | 2004/10/27 18:12 |
|          |      |  | US-PGPUB;              |                  |
|          |      |  | EPO; JPO;<br>DERWENT;  |                  |
|          |      |  | IBM TDB                |                  |
| 10       | 1    |  | USPĀT                  | 2004/10/27 18:06 |
| 11       | ī    |  | USPAT                  | 2004/10/27 18:07 |
| 12       | 1    |  | USPAT                  | 2004/10/27 18:07 |
| 13       | 2661 | 257/724                                    | USPAT;                 | 2004/10/27 18:30 |
|          |      |  | US-PGPUB;              |                  |
|          |      |  | EPO; JPO;              |                  |
|          |      |  | DERWENT;               |                  |
| 1.4      | 1000 | 257/605                                    | IBM_TDB<br>USPAT;      | 2004/10/27 18:47 |
| 14       | 1209 | 257/685                                    | US-PGPUB;              | 2004/10/2/ 10:4/ |
|          |      |  | EPO; JPO;              |                  |
|          |      |  | DERWENT;               |                  |
|          |      | 4  | IBM TDB                |                  |
| 15       | 2825 | 257/686                                    | USPAT;                 | 2004/10/27 19:06 |
| 1        |      |  | US-PGPUB;              |                  |
|          |      |  | EPO; JPO;              |                  |
|          |      |  | DERWENT;               |                  |
|          |      | 0.55 (600                                  | IBM_TDB                | 0004/10/07 10 55 |
| 16       | 2768 | 257/690                                    | USPAT;                 | 2004/10/27 19:23 |
|          |      |  | US-PGPUB;<br>EPO; JPO; |                  |
|          |      |  | DERWENT;               |                  |
|          |      |  | IBM TDB                |                  |
| 17       | 3612 | (semiconductor or die or chip or Ic) with  | USPAT                  | 2004/10/27 22:23 |
| • ·      |      | wir\$3 and solder near (ball or bump) and  |                        |                  |
|          |      | (encapsulat\$3 or mold\$3)                 |                        |                  |
| 18       | 487  | ((semiconductor or die or chip or Ic) with | USPAT                  | 2004/10/27 22:24 |
|          |      | wir\$3 and solder near (ball or bump) and  |                        |                  |
|          |      | (encapsulat\$3 or mold\$3) ) and (ball or  |                        |                  |
|          |      | bump) with (big or large)                  |                        | <u> </u>         |

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| 19       | 2749     | 257/700  | USPAT;             | 2004/10/27 20:00                     |
|----------|----------|--|--------------------|--------------------------------------|
|          |          |  | US-PGPUB;          |                                      |
|          |          |  | EPO; JPO; DERWENT; |                                      |
|          |          |  | IBM TDB            |                                      |
| 20       | 2211     | 438/108  | USPAT;             | 2004/10/27 20:25                     |
|          |          | 130/100  | US-PGPUB;          | 2001, 20, 21 20120                   |
|          |          |  | EPO; JPO;          |                                      |
|          |          |  | DERWENT;           |                                      |
|          |          |  | IBM_TDB            |                                      |
| 21       | 37       | "5844315"  | USPAT              | 2004/10/27 20:12                     |
| 22       | 1        |  | USPAT              | 2004/10/27 20:09                     |
| 23       | 1        |  | USPAT              | 2004/10/27 20:09                     |
| 24       | 1        |  | USPAT              | 2004/10/27 20:09                     |
| 25       | 1        |  | USPAT              | 2004/10/27 20:09                     |
| 26       | 1        |  | USPAT              | 2004/10/27 20:09<br>2004/10/27 20:09 |
| 27<br>28 | 1 1      |  | USPAT<br>USPAT     | 2004/10/27 20:09                     |
| 29       | 1        |  | USPAT              | 2004/10/27 20:09                     |
| 30       | 1        |  | USPAT              | 2004/10/27 20:10                     |
| 31       | 1 1      |  | USPAT              | 2004/10/27 20:11                     |
| 32       | 35       | "5608265"  | USPAT              | 2004/10/27 20:12                     |
| 33       | 1045     | 438/109  | USPAT;             | 2004/10/27 20:42                     |
|          |          |  | US-PGPUB;          |                                      |
|          |          |  | EPO; JPO;          |                                      |
| 1        |          |  | DERWENT;           |                                      |
|          |          |  | IBM_TDB            |                                      |
| 34       | 3850     | 361/760  | USPAT;             | 2004/10/27 21:34                     |
|          |          |  | US-PGPUB;          |                                      |
|          |          |  | EPO; JPO;          | '                                    |
|          |          | ,  | DERWENT;           |                                      |
| 1,5      |          | -t102 man /comicanduston on ohim on  | IBM_TDB<br>USPAT   | 2004/10/27 21:40                     |
| 37       | 0        | stack\$3 near (semiconductor or chip or die) and (lower or bottom) near              | USPAI              | 2004/10/2/ 21:40                     |
|          |          | (semiconductor or chip or die) with memory   |                    |                                      |
|          |          | and (upper or top) near (semiconductor or  |                    |                                      |
|          |          | chip or die) with microprocessor.  |                    |                                      |
| 38       | 0        | (lower or bottom) near (semiconductor or   | USPAT              | 2004/10/27 21:36                     |
|          |          | chip or die) with memory and (upper or   |                    |                                      |
|          |          | top) near (semiconductor or chip or die)   |                    |                                      |
|          |          | with microprocessor.   |                    |                                      |
| 39       | 0        | stack\$3 near (semiconductor or chip or  | USPAT              | 2004/10/27 21:37                     |
|          |          | die) and (semiconductor or chip or die)  |                    |                                      |
|          |          | near memory and (semiconductor or chip or  |                    |                                      |
| 140      | _        | die) near microprocessor.  | USPAT              | 2004/10/27 21:39                     |
| 40       | "        | stack\$3 near (semiconductor or chip or die) and (semiconductor or chip or die)      | OSEMI              | 2003/10/2/ 21.33                     |
|          | 1        | with memory and (semiconductor or chip or  |                    |                                      |
|          |          | die) with microprocessor.  |                    |                                      |
| 41       | 0        | I  | USPAT              | 2004/10/27 21:37                     |
|          |          | die) with memory and (semiconductor or   |                    |                                      |
|          |          | chip or die) with microprocessor.  |                    |                                      |
| 42       | 0        | (semiconductor or chip or die) with  | USPAT              | 2004/10/27 21:37                     |
|          |          | memory and (semiconductor or chip or die)  |                    |                                      |
| 1        |          | with microprocessor.   |                    | 0004/10/07 55 55                     |
| 43       | 0        | (semiconductor or chip or die) with  | USPAT              | 2004/10/27 21:38                     |
|          | 1        | memor\$3 and (semiconductor or chip or die)  |                    |                                      |
| 144      | 1        | with micro near processor.   | USPAT              | 2004/10/27 21:39                     |
| 44       | 0        | (semiconductor or chip or die or IC) with memor\$3 and (semiconductor or chip or die | OSEMI              | 2004/10/2/ 21:39                     |
| 1        | 1        | or IC) with microprocessor.  |                    |                                      |
| 45       | 91434    | (semiconductor or chip or die or IC) with  | USPAT              | 2004/10/27 21:38                     |
|          |          | memor\$3   |                    |                                      |
| 46       | 0        | 1  | USPAT              | 2004/10/27 21:39                     |
|          |          | microprocessor.  |                    |                                      |
| 47       | 0        | 1  | USPAT              | 2004/10/27 21:39                     |
|          |          | micro near processor.  |                    |                                      |
| 48       | 0        | [ (  | USPAT              | 2004/10/27 21:39                     |
| 1.0      |          | micro-processor.   | Henra              | 2004/10/07 21 22                     |
| 49       | 22456    | •  | USPAT              | 2004/10/27 21:39                     |
| L        | <u> </u> | microprocessor   | L                  | <del></del>                          |

| 50 | 188 |  | USPAT | 2004/10/27 21:40 |
|----|-----|--|-------|------------------|
|    |     | die) and (semiconductor or chip or die)    |       |                  |
|    |     | with memory and (semiconductor or chip or  |       |                  |
|    |     | die) with microprocessor                   |       |                  |
| 51 | 0   | stack\$3 near (semiconductor or chip or    | USPAT | 2004/10/27 21:40 |
|    |     | die) and (lower or bottom) near            |       |                  |
|    | ļ   | (semiconductor or chip or die) with memory |       |                  |
|    |     | and (upper or top) near (semiconductor or  |       | -                |
|    |     | chip or die) with microprocessor           |       |                  |
| 52 | 5   | (lower or bottom) near (semiconductor or   | USPAT | 2004/10/27 22:45 |
|    | •   | chip or die) with memory and (upper or     |       |                  |
|    | ļ   | top) near (semiconductor or chip or die)   |       |                  |
|    |     | with microprocessor                        |       |                  |
| 54 | 0   | ((semiconductor or die or chip or Ic) with | JPO   | 2004/10/27 22:24 |
|    |     | wir\$3 and solder near (ball or bump) and  |       |                  |
|    |     | (encapsulat\$3 or mold\$3) ) and (ball or  |       |                  |
|    |     | bump) with (big or large)                  |       |                  |
| 53 | 104 | 1 -  | JPO   | 2004/10/27 22:24 |
|    |     | wir\$3 and solder near (ball or bump) and  |       |                  |
|    |     | (encapsulat\$3 or mold\$3)                 |       |                  |
| 55 | 5   | · · · · · · · · · · · · · · · · · · ·      | USPAT | 2004/10/27 22:46 |
|    |     | chip or die) with memory and (upper or     |       |                  |
|    |     | top) near (semiconductor or chip or die)   |       |                  |
|    |     | with microprocessor) and (semiconductor    |       |                  |
|    |     | or chip or die) with memory and            |       |                  |
|    |     | (semiconductor or chip or die) with        |       |                  |
|    |     | microprocessor                             |       |                  |
|    | 1   | _ midlopiocobot                            | l     | L                |